

PION Contact (fine pitch solution)

- Extremely fine pitch contact solution
- Lowest cost in the market for device testing industry
- Quick turn design support for custom requirements
- Fast support for high volume production

Product Descriptions

- Applications
 - package test socket
 - wafer level test socket
 - burn-in test socket
 - interposer (PCB, socket, etc)
- Device pitch
 - 0.2 / 0.3 / 0.4 / 0.5 / 0.8mm
- Packages
 - BGA, CSP, WLCSP, QFN, etc



Advantages

- Ultra fine pitch support thru MEMS manufacturing
- Lowest cost ever any pitch type of device testing
- Quick turn design support for custom requirements
- Long insertion with good electrical properties
- Fast lead time for high volume production
- Short Length achievable

Specifications of PION contact

Item	Pitch	0.8mm	0.5mm	0.3mm	0.2mm
General Information	Length	5.80mm	8.35mm	2.0mm	2.0mm
	Diameter	0.50mm	0.35mm	0.25mm	0.15mm
	Compliance	1.0mm MAX	1.0mm MAX	0.4mm MAX	0.4mm MAX
Mechanical Characteristics	Temperature Range	-40°C ~ 125°C	-40°C ~ 125°C	-40°C ~ 125°C	-40°C ~ 125°C
	Contact Force	36~40gf@0.6mm	20~24gf@0.5mm	3.5~5.0gf@0.32mm	2.8~3.2gf@0.32mm
	Recommended Stroke	0.6mm (Test)	0.5mm (Burn-in)	0.32mm	0.32mm
	Life cycle (Mechanical)	>500K	>500K	>300K	>300K
Electrical Characteristics	Contact Resistance	<100mΩ	<100mΩ	<150mΩ	<150mΩ
	Self Inductance	2.40nH	2.85nH	0.66nH	0.58nH
	Capacitance	0.48pF	0.39pF	0.12pF	0.10pF
	Bandwidth	S21(Insertion)	9.61GHz@-1dB	5.36GHz@-1dB	14.27GHz@-1dB
		S11(Return)	1.81GHz@-20dB	0.90GHz@-20dB	6.03GHz@-20dB
	Current rate (continuous)	1.0 A	1.0 A	0.8 A	0.5 A
Material	Contact pad	Top	Au plated BeCu	Au plated BeCu	Au Plated NiCo
		Bottom	Au Plated BeCu	Au Plated BeCu	Au Plated NiCo

